Form PTO-I595 (Rev. 03-11) OMB No. 0651-0027 (exp. 03/31/2015)	U.S. DEPARTMENT OF COMMERCE United States Patent and Tradomark Office	
RECORDATION FORM COVER SHEET		
PATENTS ONLY		
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.		
Name of conveying party(ies):	2. Name and address of receiving party(ies)	
Hidenari Koshimae	Name: Sony Corporation	
	Internal Address:	
Additional name(s) of conveying party(las) attached? Yes X No	Street Address:	
3. Nature of conveyance/Execution Date(s):	1-7-1 Konan, Minato-ku	
Execution Date(s): April 26, 2012	Tokyo 108-0075	
x Assignment Merger Change of Name	JAPAN	
Security Agreement Joint Research Agreement	City:	
Government Interest Assignment	Stale:	
Executive Order 9424, Confirmatory License	Country: Zip:	
Other	Additional name(s) & address(es) Yes X No	
13/490,551 Additional numbers attached?	Yes X No	
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:	
Name: Dennis M. Smid, Esq. LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00	
Internal Address: Atty, Dkt.; SONYJP 3.0-2811		
Street Address: 600 South Avenue West	X Authorized to be charged to deposit account	
	Enclosed	
	None required (government interest not affecting title)	
City: Westfield	8. Payment Information	
State: NJ Zip: 07090	•	
Phone Number: 908-654-5000		
Fax Number: 908-654-7866	Deposit Account Number 12-1095	
Email Address:ataylor@ldlkm.com	Authorized User Name Dennis M. Smld, Esq.	
9. Signature:	June 7, 2012	
Signature	Date	
Dennis M. Smid, Esq 34,930	Total number of pages Including cover 2	
Name of Person Signing	sheet, attachments, and documents;	

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PATENT REEL: 028373 FRAME: 0028

Attorney Docket No. SONYJP 3.0-2811 SONY Ref. No.; SP316930US00

ASSIGNMENT

LDLKM

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING DEVICE, INFORMATION PROCESSING METHOD, AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made'or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filling date of this application in

the spaces that follow: Serial Number: 13/490,551	Filing Date: June 7, 2012
This assignment executed on the dates indicated below.	
HIDENARI KOSHIMAE	
Name of first or sole inventor TOKYO, JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor Hidenari Koshinae	April 26, 2012
Signature of first or sole inventor	Date of this assignment
Name of second inventor	Execution date of U.S. Patent Application
Residence of second inventor	
Signature of second inventor	Date of this assignment
Name of third inventor	Execution date of U.S. Patent Application
Residence of third inventor	
Signature of third inventor	Date of this assignment

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